

To: **Technology Unit: 2814**  
**Facsimile Number: 703-872-9306**


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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

CERTIFICATION OF FACSIMILE TRANSMISSION  I hereby certify that the following papers are being transmitted by facsimile to the U.S. Patent and Trademark Office at 703-872-9306 on the date shown below:   Tommie Chambers <span style="float: right;">11-12-04</span> Date	
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NAME OF INVENTOR(S): Yew	RECEIPT DATE & SERIAL NO.: Serial No.: 10/612,129 Filing Date: 7/2/2003
TITLE OF INVENTION: DIRECT ATTACHMENT OF SEMICONDUCTOR CHIP TO ORGANIC SUBSTRATE	
TI FILE NO.: TI-26239.1	DEPOSIT ACCT. NO.: 20-0668
FAXED: 11-12-04 DUE: 11/08/2004 ATTY/SECY: WDS/tic	

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Texas Instruments Incorporated  
 PO Box 655474, M/S 3999  
 Dallas, TX 75265

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Yew, et al.

Docket No: TI-26239.1

Serial No: 10/612,129

Examiner: Cao, Phat X.

Filed: 7/2/2003

Art Unit: 2814

For: DIRECT ATTACHMENT OF SEMICONDUCTOR CHIP TO ORGANIC SUBSTRATE

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**NOTICE OF APPEAL FROM THE PRIMARY EXAMINER  
TO THE BOARD OF APPEALS**

Assistant Commissioner for Patents

PO Box 1450

Alexandria, VA 22313-1450

Dear Sir:

CERTIFICATION OF FACSIMILE TRANSMISSION I hereby  
certify that the following papers are being transmitted by  
facsimile to the U.S. Patent and Trademark Office at 703-872-  
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*Tommie Chambers*  
Tommie Chambers  
11-12-04

Applicant hereby appeals to the Board of Appeals from the decision mailed August 6, 2004, of the  
Primary Examiner finally rejecting Claims 1-2, and 4-15.

The item(s) checked below are appropriate:

1. ☒ An extension of time to respond to the final rejection  
\_\_\_\_\_ was granted on \_\_\_\_\_.  
☒ is requested for 1 month.
2. ☐ A timely response to the final rejection has been filed, as provided in  
841 O.G. 1411.
3. ☒ Fee \$340.00:  
☐ Not required (Fee paid in prior appeal)  
☒ The Commissioner of Patents is hereby authorized to charge any  
fees which may be required or credit any overpayment to the deposit  
account of Texas Instruments Incorporated, Account No. 20-0668.  
This form is submitted in duplicate.

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